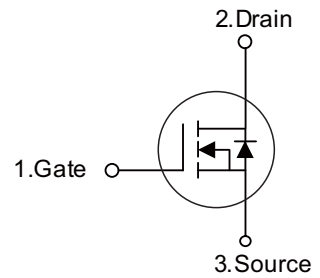


■ PRODUCT CHARACTERISTICS

V <sub>DSS</sub>	60
R <sub>DS(ON)</sub> Typ(@V <sub>GS</sub> =10V)	18mΩ
Q <sub>g</sub> @typ	48nC
I <sub>D</sub>	55A

Symbol

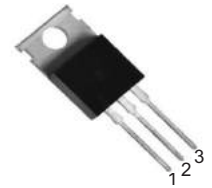


■ APPLICATIONS

- \* Electronic lamp ballasts based on half bridge
- \* Load Switching, Quick/Wireless Charge.
- \* Motor Driving

■ FEATURE

- \* Low Gate Charge
- \* Pb-Free Lead Plating



TO-220C

■ ORDER INFORMATION

Order Codes		Package	Packing
Halogen-Free	Halogen		
N/A	MOT55N06B	TO-22C	50 pieces/Tube

■ ABSOLUTE MAXIMUM RATINGS(T<sub>A</sub>=25°C, unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V <sub>DSS</sub>	60	V
Gate-Source Voltage	V <sub>GSS</sub>	±20	V
Drain Current Continuous(@V <sub>GS</sub> =10V, T <sub>A</sub> =25°C)	I <sub>D</sub>	55	A
Drain Current Continuous(@V <sub>GS</sub> =10V, T <sub>A</sub> =100°C)	I <sub>D</sub>	34	A
Drain Current Pulsed	I <sub>DM</sub>	220	A
Avalanche Energy *	E <sub>AS</sub>	600	mJ
Power Dissipation	P <sub>D</sub>	100	W
Junction Temperature	T <sub>J</sub>	+150	°C
Storage Temperature	T <sub>STG</sub>	-55~ +150	°C

■ THERMAL CHARACTERISTICS

Parameter	Symbol	Typ	Unit
Junction to Case	R <sub>thJC</sub>	1.25	°C/W

Note: \* EAS condition: T<sub>J</sub>=25°C, V<sub>DD</sub>=30V, V<sub>G</sub>=10V, L=0.5mH, R<sub>g</sub>=25Ω

**■ ELECTRICAL CHARACTERISTICS** ( $T_C=25^{\circ}\text{C}$ , unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Off characteristics						
Drain to Source Breakdown Voltage	$V_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	60	-	-	V
Drain to Source Leakage Current	$I_{DSS}$	$V_{DS}=60V, V_{GS}=0V$	-	-	1	$\mu A$
Gate to Source Forward Leakage	$I_{GSS(F)}$	$V_{GS}=+20V, V_{DS}=0V$	-	-	100	nA
Gate to Source Reverse Leakage	$I_{GSS(R)}$	$V_{GS}=-20V, V_{DS}=0V$	-	-	-100	nA
On characteristics						
Drain to Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=20A$	-	18	22	m $\Omega$
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	2	3.2	4	V
Dynamic characteristics						
Gate capacitance	$R_g$	$V_{GS}=0V, V_{DS}=0V, f=1.0\text{MHz}$	-	1	-	$\Omega$
Forward Transconductance	$g_{fs}$	$V_{DS}=10V, I_D=3A$	-	9	-	S
Input Capacitance	$C_{iss}$	$V_{DS}=30V, V_{GS}=0V$ $f=1.0\text{MHz}$	-	1478	-	pF
Output Capacitance	$C_{oss}$		-	313	-	pF
Reverse Transfer Capacitance	$C_{rss}$		-	85	-	pF
Resistive Switching Characteristics						
Turn-on Delay Time	$t_{d(ON)}$	$V_{GS}=10V, V_{DS}=30V,$ $I_D=20A, R_G=3\Omega$	-	12	-	ns
Rise Time	$t_r$		-	28	-	ns
Turn-off Delay Time	$t_{d(OFF)}$		-	29	-	ns
Fall Time	$t_f$		-	11	-	ns
Total Gate Charge	$Q_g$	$I_D=20A, V_{DS}=30V$ $V_{GS}=10V$	-	43	-	nC
Gate to Source Charge	$Q_{gs}$		-	13	-	nC
Gate to Drain("Miller") Charge	$Q_{gd}$		-	18	-	nC
Source-Drain Diode Characteristics						
Continuous Source Current(Body Diode)	$I_S$		-	-	55	A
Maximum Pulsed Current(Body Diode)	$I_{SM}$		-	-	220	A
Diode Forward Voltage	$V_{SD}$	$I_{SD}=3A, V_{GS}=0V$	-	0.74	1.2	V
Reverse Recovery Time	$t_{rr}$	$I_{SD}=20A, T_J=25^{\circ}\text{C}$ $di/dt=100A/\mu s$	-	23	-	ns
Reverse Recovery Charge	$Q_{rr}$		-	26	-	nC

■ TYPICAL CHARACTERISTICS

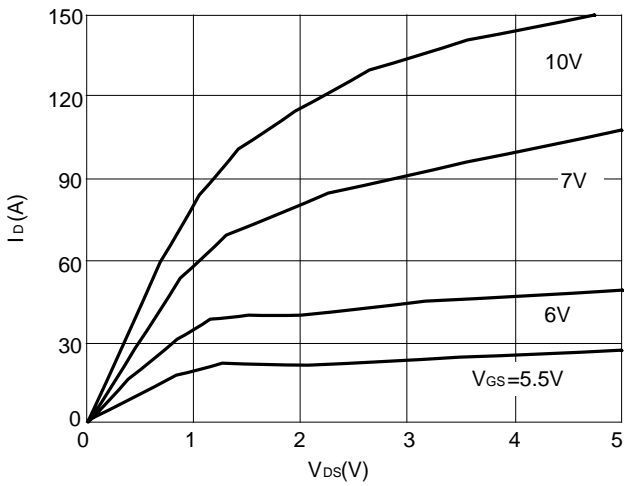


Figure 1: Output Characteristics

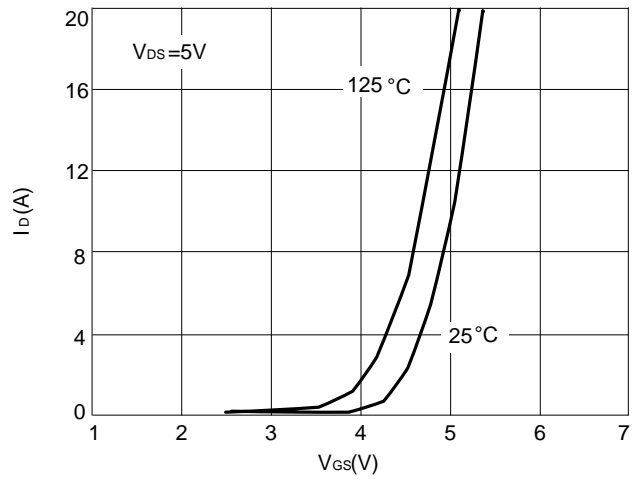


Figure 2: Transfer Characteristics

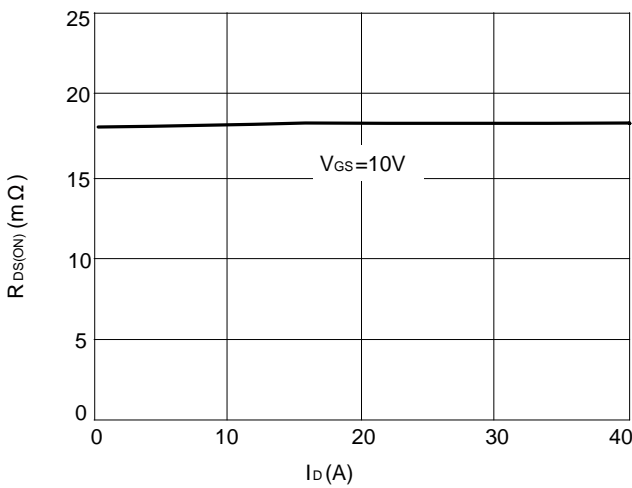


Figure 3:  $R_{DS(ON)}$  vs. Drain Current

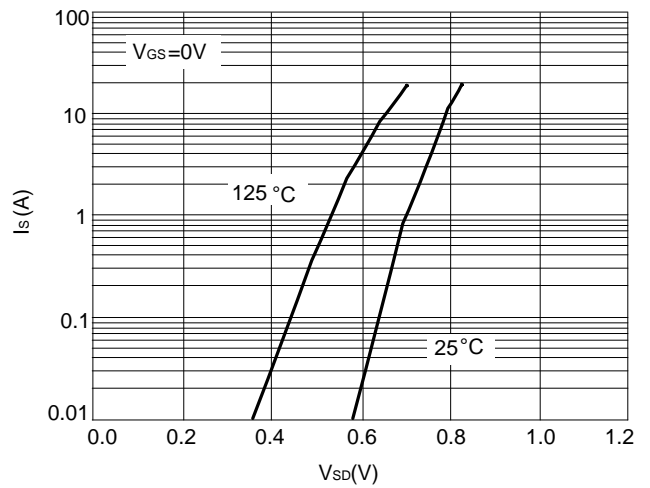


Figure 4: Body Diode Characteristics

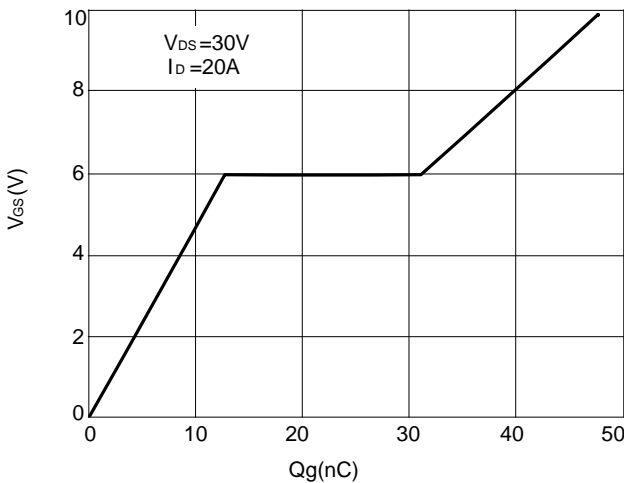


Figure 5: Gate Charge Characteristics

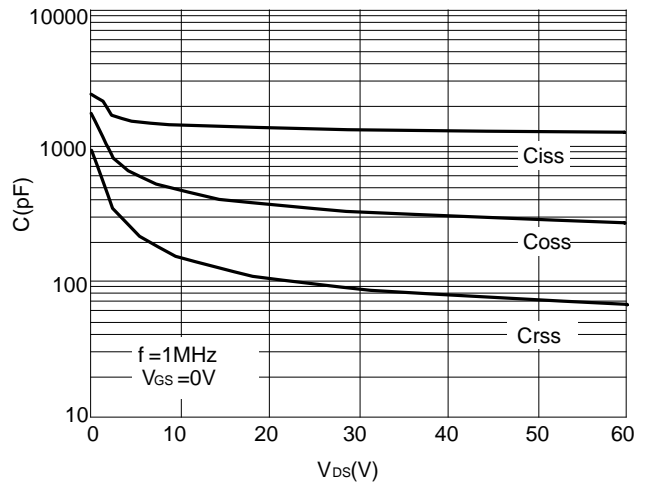


Figure 6: Capacitance Characteristics

■ TYPICAL CHARACTERISTICS

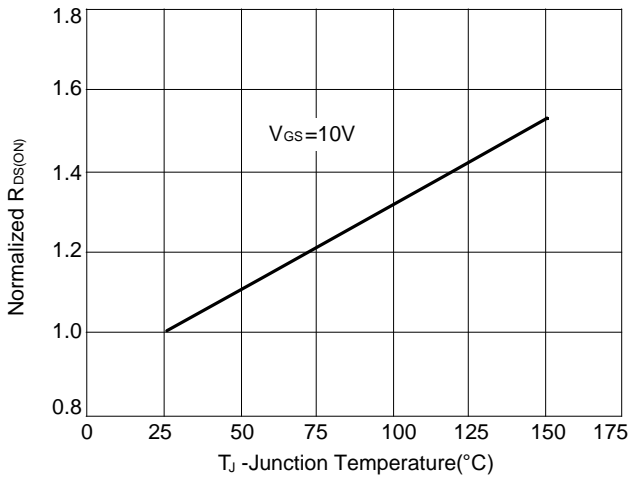


Figure 7: Normalized on Resistance vs. Junction Temperature

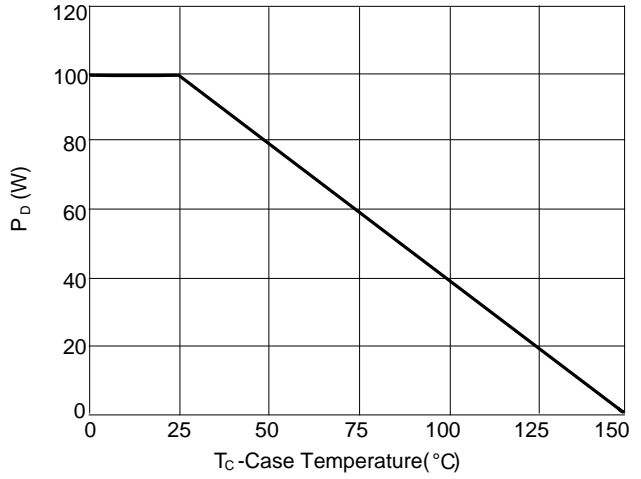


Figure 8: Power De-rating

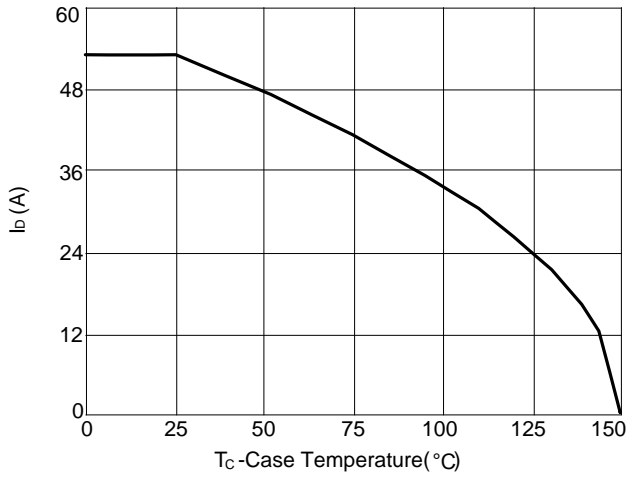


Figure 9: Current De-rating

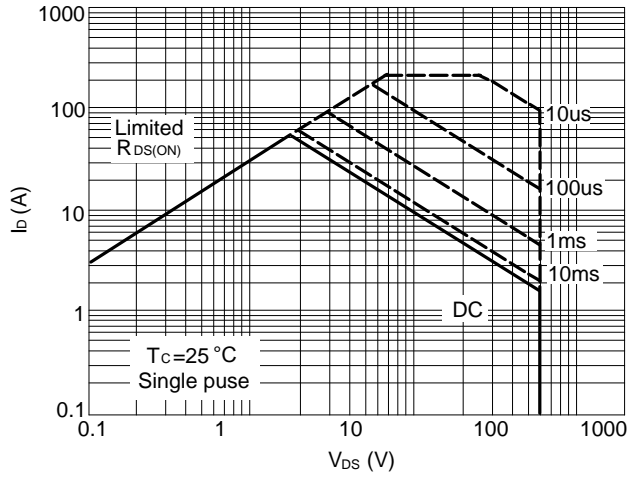


Figure 10: Maximum Safe Operating Area

